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I.S. EN 61188-5-6:2003

ICS 31.190



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EUROPEAN STANDARD

EN 61188-5-6

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2003

ICS 31.190

English version

Printed boards and printed board assemblies – Design and use Part 5-6: Attachment (land/joint) considerations – Chip carriers with J-leads on four sides (IEC 61188-5-6:2003)

Cartes imprimées et cartes imprimées équipées – Conception et utilisation Partie 5-6: Considérations sur les liaisons pistes-soudures – Composants à sorties en J sur quatre côtés (CEI 61188-5-6:2003) Leiterplatten und Flachbaugruppen -Konstruktion und Anwendung Teil 5-6: Betrachtungen zur Montage (Anschlussfläche/Verbindung) -Bauelemente mit J-förmigen Anschlüssen auf vier Seiten (IEC 61188-5-6:2003)

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CENELEC

European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

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EN 61188-5-6:2003

- 2 -

Foreword

The text of document 91/338/FDIS, future edition 1 of IEC 61188-5-6, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61188-5-6 on 2003-03-01.

This European Standard should be read in conjunction with EN 61188-5-1:2002.

The following dates were fixed:

-	latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop) 2003-12-01
-	latest date by which the national standards conflicting with the EN have to be withdrawn	(dow) 2006-03-01

Annexes designated "normative" are part of the body of the standard. In this standard, annex ZA is normative. Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 61188-5-6:2003 was approved by CENELEC as a European Standard without any modification.

- 3 -

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	<u>EN/HD</u>	Year
IEC 60068-2-58	- 1)	Environmental testing Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	1999 ²⁾
IEC 60191-2	_ 1)	Mechanical standardization of semiconductor devices Part 2: Dimensions	-	-
IEC 61188-5-1	_ 1)	Printed boards and printed board assemblies - Design and use Part 5-1: Attachment (land/joint) considerations - Generic requirements	EN 61188-5-1	2002 ²⁾
IEC 61760-1	_ 1)	Surface mounting technology Part 1: Standard method for the specification of surface mounting components (SMDs)	EN 61760-1	1998 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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Première édition First edition 2003-01

Cartes imprimées et cartes imprimées équipées – Conception et utilisation –

Partie 5-6: Considérations sur les liaisons pistes-soudures – Composants à sorties en J sur quatre côtés

Printed boards and printed board assemblies – Design and use –

Part 5-6: Attachment (land/joint) considerations – Chip carriers with J-leads on four sides



Numéro de référence Reference number CEI/IEC 61188-5-6:2003



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